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CONFIRMATION NO. 9336

<b>SERIAL NUMBER</b> 10/657,505	<b>FILING OR 371(c) DATE</b> 09/08/2003 <b>RULE</b>	<b>CLASS</b> 438	<b>GROUP ART UNIT</b> 2812	<b>ATTORNEY DOCKET NO.</b> TS01-1247	
<b>APPLICANTS</b> Chii-Ming Wu, Taipei, TAIWAN; Ming-Hsing Tsai, Taipei, TAIWAN; Ching-Hua Hsieh, Hsinchu, TAIWAN; Shau-Lin Shue, Hsinchu, TAIWAN; <i>SDG</i>					
<b>** CONTINUING DATA *****</b> <i>NONE</i> <i>SDG</i>					
<b>** FOREIGN APPLICATIONS *****</b> <i>NONE</i> <i>SDG</i>					
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 12/16/2003</b>					
Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after met Verified and Acknowledged <i>Mr. B</i> Allowance <i>SDG</i> Examiner's Signature Initials		<b>STATE OR COUNTRY</b> TAIWAN	<b>SHEETS DRAWING</b> 6	<b>TOTAL CLAIMS</b> 51	<b>INDEPENDENT CLAIMS</b> 5
<b>ADDRESS</b> 42717					
<b>TITLE</b> Method of manufacturing a contact interconnection layer containing a metal and nitrogen by atomic layer deposition for deep sub-micron semiconductor technology					
<b>FILING FEE RECEIVED</b> 1476	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		